

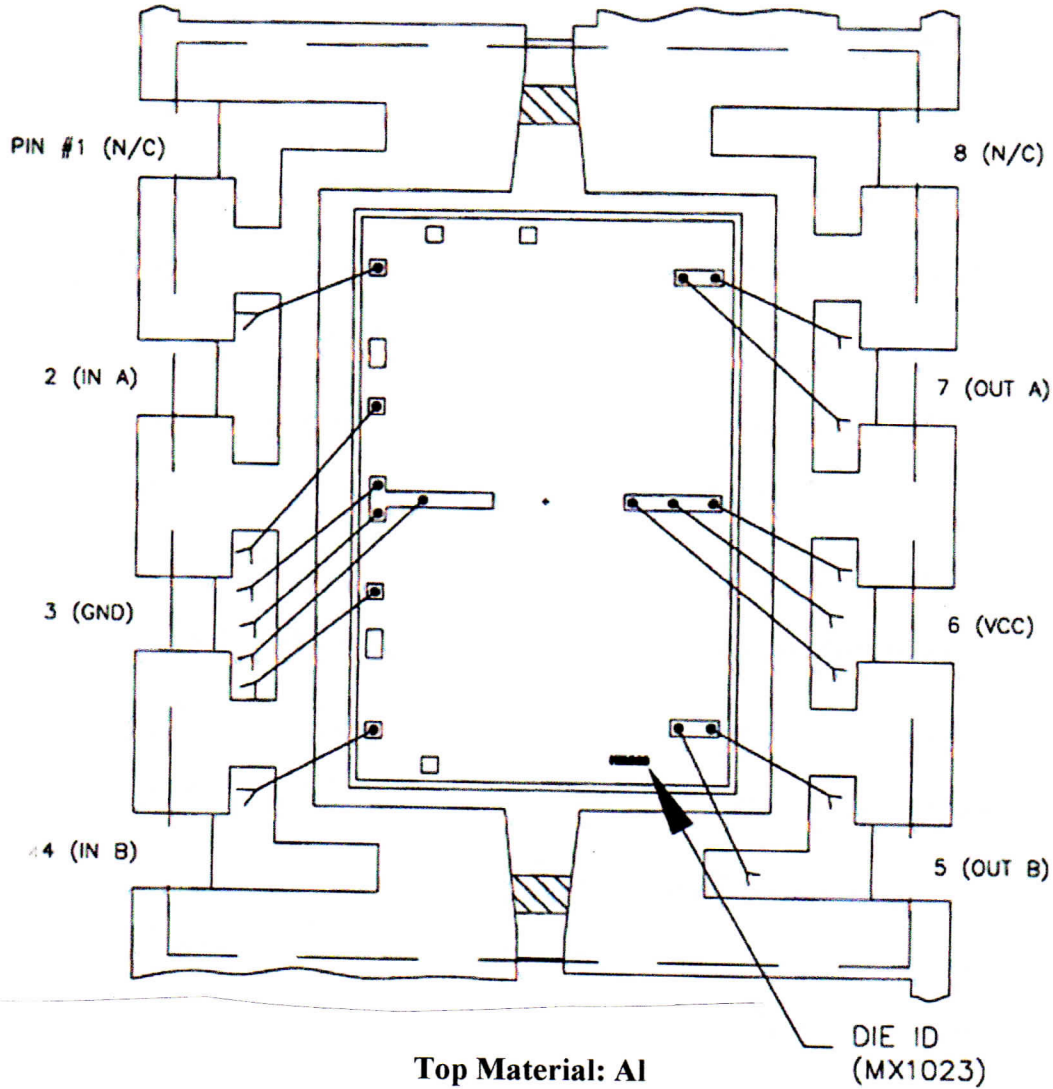


# Sierra Components, Inc.

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Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.



Top Material: Al  
 Backside Material: TiNiAg  
 Bond Pad Size: .004" X .004" min.  
 Backside Potential:  
 Mask Ref:

APPROVED BY: DK

DIE SIZE .081 X .122"

DATE: 4/28/16

MFG: IXYS

THICKNESS .012"

P/N: IXDN604